

Application No.: 10/707,507

Docket No.: 22171-00011-US

AMENDMENTS TO THE CLAIMS

This claim listing replaces all previous listings of claims in this application.

1. (Currently amended) An integrated circuit probe card comprising:
a plurality of probes separated by a first pitch;
~~a circuit board consisting including~~ a plurality of ~~laminated boards~~
laminates and having an upper surface and a bottom surface,
comprising:
a plurality of testing pads provided on the upper surface and separated
by a second pitch larger than the first pitch, and being able to be
electrically connected to a test machine directly; and
a plurality of conductive wires provided inside the circuit board, ~~for~~
~~connecting the testing pads to the bottom surface;~~ and
~~a plurality of probes separated by a first pitch and being electrically~~
~~connected to the conductive wires, wherein the first pitch is smaller~~
~~than the second pitch~~
wherein the conductive wires are separated by the second pitch in an
uppermost laminate and separated by the first pitch in a bottommost
laminate for electrically connecting the testing pads to the probes.
2. (Currently amended) The integrated circuit probe card of Claim 1,
wherein the circuit board is constituted by tightly stacking up a
plurality of ~~laminated boards~~ laminates.
3. (Original) The integrated circuit probe card of Claim 1, wherein the
circuit board can further comprises a plurality of electronic devices
provided on the upper surface for processing testing signals.
4. (Original) The integrated circuit probe card of Claim 1, wherein the
first pitch is smaller than 400 micrometer.

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5. (Original) The integrated circuit probe card of Claim 1, wherein the plurality of probes are directly in contact with the conductive wires.
6. (Original) The integrated circuit probe card of Claim 1, wherein the first pitch is approximately the same as the pitch between signal pads of an integrated circuit device under test.